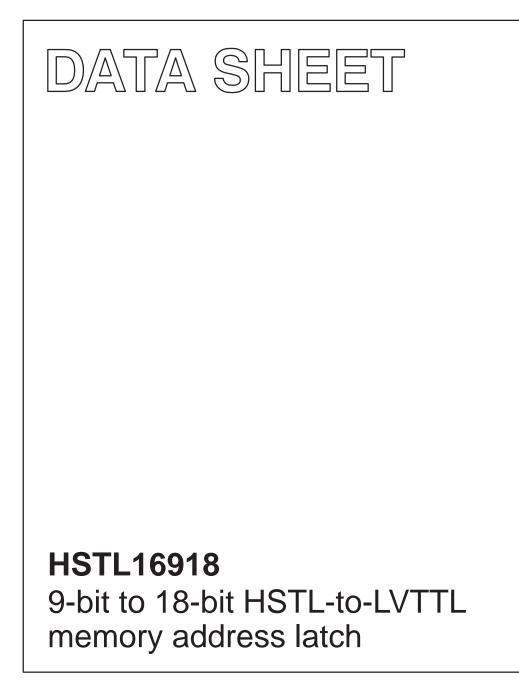
# INTEGRATED CIRCUITS



Product data

2001 Jun 16



Philips Semiconductors

### **HSTL16918**

### **FEATURES**

- Inputs meet JEDEC HSTL Std. JESD 8-6, and outputs meet Level III specifications
- ESD classification testing is done to JEDEC Standard JESD22. Protection exceeds 2000 V to HBM per method A114.
- Latch-up testing is done to JEDEC Standard JESD78, which exceeds 100 mA.
- Packaged in 48-pin plastic thin shrink small outline package (TSSOP48)

### DESCRIPTION

The HSTL16918 is a 9-bit to 18-bit D-type latch designed for 3.15 to 3.45 V  $V_{CC}$  operation. The D inputs accept HSTL levels and the Q outputs provide LVTTL levels.

The HSTL16918 is particularly suitable for driving an address bus to two banks of memory. Each bank of nine outputs is controlled with its own latch-enable  $(\overline{LE})$  input.

Each of the nine D inputs is tied to the inputs of two D-type latches that provide true data (Q) at the outputs. While  $\overline{LE}$  is LOW the Q outputs of the corresponding nine latches follow the D inputs. When LE is taken HIGH, the Q outputs are latched at the levels set up at the D inputs.

The HSTL16918 is characterized for operation from 0 to +70 °C.

PIN CONFIGURATION	N
2Q1 1	48 V <sub>CC</sub>
1Q1 2	47 V <sub>CC</sub>
GND 3	46 1Q2
D1 4	45 2Q2
D2 5	44 GND
V <sub>CC</sub> 6	43 1Q3
D3 7	42 2Q3
D4 8	41 V <sub>CC</sub>
GND 9	40 1Q4
1LE 10	39 2Q4
GND 11	38 GND
V <sub>REF</sub> 12	37 1Q5
GND 13	36 2Q5
2LE 14	35 GND
GND 15	34 1Q6
D5 16	33 2Q6
D6 17	32 V <sub>CC</sub>
D7 18	31 1Q7
V <sub>CC</sub> [19	30 2Q7
D8 20	29 GND
D9 21	28 1Q8
GND 22	27 2Q8
2Q9 23	26 V <sub>CC</sub>
1Q9 24	25 V <sub>CC</sub>

### **ORDERING INFORMATION**

PACKAGES	TEMPERATURE RANGE	ORDER CODE	DWG NUMBER
48-pin plastic thin shrink small outline package (TSSOP48)	0 to +70 °C	HSTL16918DGG	SOT362-1

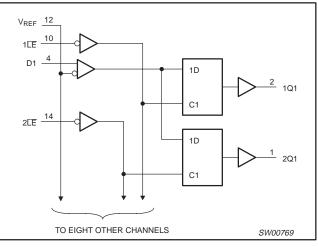
### 

### HSTL16918

### **PIN DESCRIPTION**

PIN	SYMBOL	FUNCTION
4, 5, 7, 8, 16, 17, 18, 20, 21	D[1–9]	Inputs
2, 46, 43, 40, 37, 34, 31, 28, 24	1Q[1–9]	Outputo
1, 45, 42, 39, 36, 33, 30, 27, 23	2Q[1-9]	Outputs
10	1LE	Latch enable
14	2LE	Laten enable
12	V <sub>REF</sub>	Reference voltage
6, 19, 25, 26, 32, 41, 47, 48	V <sub>CC</sub>	Supply voltage
3, 9, 11, 13, 15, 22, 29, 35, 38, 44	GND	Ground

### LOGIC DIAGRAM (positive logic)



### **FUNCTION TABLE**

INP	OUTPUT	
LE	D	Q
L	Н	Н
L	L	L
н	х	Q <sub>0</sub> <sup>1</sup>

**NOTE:** 1. Output level before the indicated steady-state input conditions were established.

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### ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

Over operating free-air temperature range (unless otherwise noted).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5 to +4.6	V
VI	Input voltage range <sup>2</sup>		–0.5 to V <sub>CC</sub> +0.5	V
Vo	Output voltage range <sup>2</sup>		–0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0	-50	mA
I <sub>OK</sub>	Output clamp current <sup>3</sup>	$V_{O} < 0 \text{ or } V_{O} > V_{CC}$	±50	mA
Ι <sub>Ο</sub>	Continuous output current	$V_{O} = 0$ to $V_{CC}$	±50	mA
	Continuous current through each $V_{CC}$ or GND		±100	mA
$\theta_{JA}$	Package thermal impedance <sup>4</sup>		89	°C/W
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. 3. This current flows only when the output is in the high state and  $V_O > V_{CC}$ . 4. The package thermal impedance is calculated in accordance with JESD 51.

### **RECOMMENDED OPERATING CONDITIONS<sup>1</sup>**

SYMBOL	DL PARAMETER			LIMITS		UNIT
STMBOL			Min	Nom	Max	UNIT
V <sub>CC</sub>	Supply voltage		3.15		3.45	V
V <sub>REF</sub>	Reference voltage		0.68	0.75	0.9	V
VI	Input voltage		0		1.5	V
V <sub>IH</sub>	AC high-level input voltage	All inputs	V <sub>REF</sub> + 200 mV			V
V <sub>IL</sub>	AC low-level input voltage	All inputs			$V_{REF}$ – 200 mV	V
V <sub>IH</sub>	DC high-level input voltage	All inputs	V <sub>REF</sub> + 100 mV			V
V <sub>IL</sub>	DC low-level input voltage	All inputs			V <sub>REF</sub> – 100 mV	V
I <sub>ОН</sub>	High-level output current				-24	mA
I <sub>OL</sub>	Low-level output current				24	mA
T <sub>amb</sub>	Operating free-air temperature range		0		+70	°C

NOTE:

1. All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation.

# HSTL16918

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### ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range (unless otherwise noted).

	DADAMETER	PARAMETER TEST CONDITIONS		LIMITS		
SYMBOL	PARAMETER	TEST CONDITIONS	Min	Typ <sup>1</sup>	Max	UNIT
V <sub>IK</sub>		$V_{CC} = 3.15 \text{ V}; \text{ I}_{\text{I}} = -18 \text{ mA}$			-1.2	V
V <sub>OH</sub>		$V_{CC} = 3.15 \text{ V}; \text{ I}_{OH} = -24 \text{ mA}$	2.4			V
V <sub>OL</sub>		V <sub>CC</sub> = 3.15 V; I <sub>OL</sub> = 24 mA			0.5	V
	Control inputs	$V_{CC} = 3.45 \text{ V}; \text{ V}_{I} = 0 \text{ or } 1.5 \text{ V}$			±5	μA
li li	Data inputs	$V_{CC} = 3.45 \text{ V}; \text{ V}_{I} = 0 \text{ or } 1.5 \text{ V}$			±5	μΑ
	V <sub>REF</sub>	$V_{CC}$ = 3.45 V; $V_{REF}$ = 0.68 V or 0.9 V			90	μA
I <sub>CC</sub>		$V_{CC} = 3.45 \text{ V}; \text{ V}_{I} = 0 \text{ or } 1.5 \text{ V}$		50	100	mA
	Control inputs	$V_{CC}$ = 0 or 3.3 V; $V_{I}$ = 0 or 3.3 V		2		pF
Cl	Data inputs	$V_{CC} = 0 \text{ or } 3.3 \text{ V}; \text{ V}_{I} = 0 \text{ or } 3.3 \text{ V}$		2.5		pF
CO	Outputs	$V_{CC} = 0 V; V_{O} = 0 V$		4		pF

NOTE:

1. All typical values are at V<sub>CC</sub> = 3.3 V; T<sub>amb</sub> = 25 °C.

### TIMING REQUIREMENTS

Over recommended operating free-air temperature range (unless otherwise noted).

SYMBOL	PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 3.3	UNIT	
STMBOL	PARAMETER	TEST CONDITIONS	Min	Max	UNIT
t <sub>w</sub>	Pulse duration	LE LOW (Figure 1)	3		ns
t <sub>su</sub>	Setup time	D before $\overline{\text{LE}} \uparrow$ (Figure 2)	2		ns
t <sub>h</sub>	Hold time	D after $\overline{\text{LE}}$ (Figure 2)	1		ns
t <sub>ldr</sub>	Data race condition time <sup>1</sup>	D after $\overline{\text{LE}} \downarrow$		0	ns

NOTE:

1. This is the maximum time after LE switches LOW that the data input can return to the latched state from the opposite state without producing a glitch on the output.

### SWITCHING CHARACTERISTICS

Over recommended operating free-air temperature range;  $V_{REF} = 0.75$  V.

SYMBOL	PARAMETER FRO		FROM TO		$V_{CC}$ = 3.3 V $\pm 0.15$ V		
STWBOL	(INPUT)	(OUTPUT)	Min	Мах	UNIT		
	Dropogation dolou (Figure 2)	D	Q	1.9	3.4	ns	
t <sub>pd</sub>	Propagation delay (Figure 3)	LE	Q	1.9	4.2	ns	

### SIMULTANEOUS SWITCHING CHARACTERISTICS

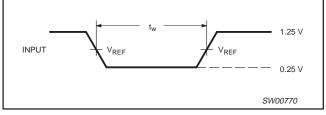
Over recommended operating free-air temperature range; V<sub>REF</sub> = 0.75 V

SYMBOL			PARAMETER FROM		то	$V_{CC}$ = 3.3 V $\pm 0.15$ V		UNIT
STWBOL	PARAIVETER	(INPUT)	(OUTPUT)	Min	Мах			
	Propagation delay; all outputs switching	D	Q	1.9	4.4	ns		
<sup>L</sup> pd	(Figure 3)	LE	Q	1.9	5.2	ns		

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### **VOLTAGE WAVEFORMS**





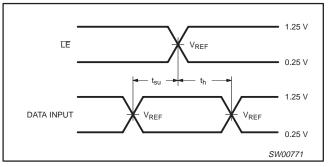


Figure 2. Setup and Hold times

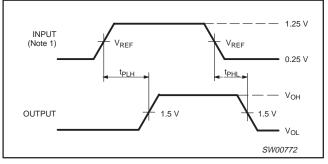
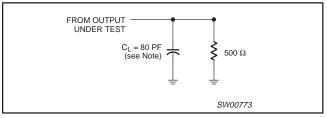


Figure 3. Propagation delay times

#### NOTES:

- 1. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  1 ns, t<sub>f</sub>  $\leq$  1 ns.
- 2. The outputs are measured one at a time with one transition per measurement.
- 3.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}.$

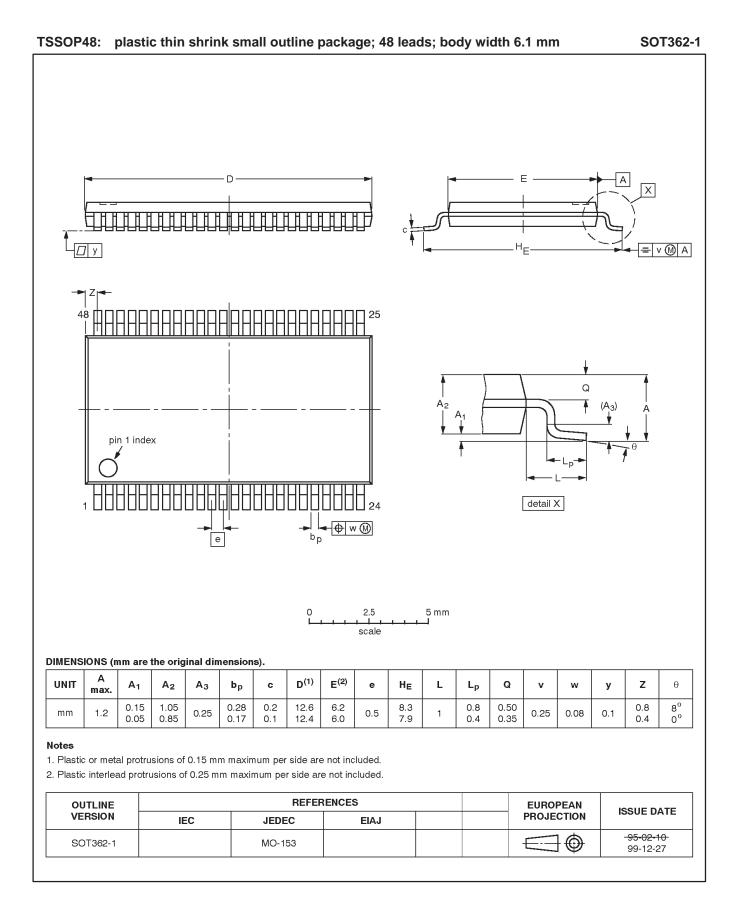
### LOAD CIRCUIT



NOTE: C<sub>L</sub> includes probe and jig capacitance. Figure 4. Load circuit



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### Data sheet status

Data sheet status <sup>[1]</sup>	Product status <sup>[2]</sup>	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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**Philips Semiconductors** 811 East Arques Avenue P.O. Box 3409 Sunnyvale, California 94088-3409 Telephone 800-234-7381

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